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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously Presented) A method of forming an active area surrounded with an insulating area in a semiconductor substrate, comprising the steps of:

- a) forming in the substrate a trench surrounding an active area;
- b) filling the trench with an insulating material to form an edge extending beyond a surface of the substrate at a periphery of the active area;
- c) forming a spacer at a periphery of said edge;
- d) implanting a dopant of a first type only to provide a channel zone of a MOS transistor in the active area, whereby the implantation in an area located under the spacer is less deep than in the rest of the active area; and
- e) forming a conductive gate on the active area after the implanting step without implanting any dopants of other than the first type in the active area prior to forming the conductive gate.

2. (Original) The method of claim 1, wherein the spacer has a substantially vertical edge or has a bell shape, with a thickness that thins down as the distance from said edge increases.

3. (Previously Presented) The method of claim 1, wherein the implantation step is followed by a step of removing the spacer prior to forming the conductive gate.

4. (Original) The method of claim 3, wherein the step of removing the spacer is preceded or followed by a step of implantation of another active area with a dopant of another conductivity type than that of the dopant used at step d).

5. (Previously Presented) The method of claim 1, further comprising a step of forming, at the surface of the active area, a protective coating between the trench filling step and spacer forming step c).

6. (Original) The method of claim 5, wherein the protective coating results from the thermal growth of a thin silicon oxide layer at the surface of the substrate.

7. (Original) The method of claim 1, wherein the spacer is made of silicon nitride.

8. (Original) The method of claim 1, wherein the spacer is made of polysilicon.

9. (Cancelled)

10. (Cancelled)

11. (Cancelled)

12. (Cancelled)

13. (Currently Amended) A method of forming a doped active area in a semiconductor substrate, comprising:

forming first and second insulation areas on a surface of the substrate, the first and second insulation areas being spaced apart from each other and thereby defining a substrate region of the substrate between the first and second insulation areas, the substrate region having a first peripheral portion immediately adjacent to the first insulation area and a central portion spaced apart from the first insulation area;

forming a first spacer adjacent to the first insulation area and above the first peripheral portion of the substrate region, the first spacer having a concave surface; and

performing, after forming the first spacer, a first dopant implant into the substrate region to create the doped active area, the first spacer acting as a mask to allow dopants to extend deeper into the central portion ~~that~~ than into the first peripheral portion.

14. (Previously Presented) The method of claim 13 wherein the substrate region has a second peripheral portion immediately adjacent to the second insulation area, the method further comprising forming a second spacer adjacent to the second insulation area and above the second peripheral portion of the substrate region, wherein performing the first dopant implant is executed after forming the second spacer, the second spacer acting as a mask to allow dopants to extend deeper into the central portion than into the second peripheral portion

15. (Original) The method of claim 13, further comprising:
forming in the substrate first and second trenches on opposite sides of the substrate region, wherein forming the first and second insulation areas includes filling the trenches with insulating material and extending the insulating material to a level above a surface of the substrate region.

16. (Original) The method of claim 15 wherein the first dopant implant forms a first well that extends into the substrate region to a first level and the first and second trenches extend into the substrate to a second level, the method further comprising performing a second dopant implant into the substrate region, thereby forming a second well that extends into the substrate region to the second level.

17. (Original) The method of claim 13, wherein the first spacer has a bell shape with a thickness that thins down as the distance from the first insulation area increases.

18. (Original) The method of claim 13, further comprising:

removing the first spacer after performing the first dopant implant; and
depositing a first conductive layer on the substrate region.

19. (Original) The method of claim 13, further comprising forming a protective coating directly on the substrate region before forming the first spacer, the first spacer being formed on the protective coating.

20. (Original) The method of claim 13 wherein the first spacer is made of silicon nitride.

21. (Previously Presented) A method of forming a doped active area in a semiconductor substrate, comprising:

forming first and second insulation areas on a surface of the substrate, the first and second insulation areas being spaced apart from each other and thereby defining a substrate region of the substrate between the first and second insulation areas, the substrate region having a first peripheral portion immediately adjacent to the first insulation area and a central portion spaced apart from the first insulation area;

forming a spacer adjacent to the first insulation area and above the first peripheral portion of the substrate region;

performing, with the spacer positioned above the substrate, a high-energy first implant of first dopant type into the substrate region to create a well that extends in the substrate at a bottom side of the first insulation area; and

performing, with the spacer positioned above the substrate, a low-energy second implant of the first dopant type into the substrate region to create the doped active area, the spacer acting as a mask to allow dopants of the second implant to extend deeper into the central portion than into the first peripheral portion.

22. (Previously Presented) The method of claim 21, further comprising forming a conductive gate on the active area after performing the first and second implants

without implanting any dopants of other than the first dopant type in the active area prior to forming the conductive gate.

23. (Cancelled)

24. (Previously Presented) The method of claim 21, further comprising planarizing top surfaces of the insulating areas after performing the second implant.